



Customer Information Notification

2022070271 : GD3100 Design Change With Errata Removal, Safety Manual and Data Sheet Updates

Note: This notice is NXP Company Proprietary.

Issue Date: Nov 30, 2022 **Effective date:** Dec 30, 2022

Dear Collette Sannes-Neste,

Here is your personalized notification about a NXP general announcement.

For detailed information we invite you to [view this notification online](#)

Management summary

New GD3100 pass 3.0 silicon revision for manufacturability improvements and Errata removal, along with Safety Manual and Data Sheet updates.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input checked="" type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

NXP Semiconductors announces the release of silicon revision pass 3.0 for the GD3100 family of devices to correct previous errata and introduce manufacturability improvements. See new Errata Sheet update revision 7.0, Safety Manual update revision 6.0, and Data Sheet update revision 13.0. There is no impact on hardware or software between previous silicon revision and new silicon revision. The revision history included in the updated documents provides a detailed description of the changes.

GD3100 Errata Sheet ES_GD3100 revision 7.0

1. Removed errata ER2 (Momentary gate turn-off during overtemperature warning) by improving VGEMON_INTB internal coil filtering used to report faults. OTW can now be used without limitation on pass 3.0.
2. Removed errata ER3 (Excessive current draw by gate hold off during a VCCREG undervoltage condition) by modifying holdoff enable logic circuitry, no longer tied to VCCREG_UV.

New GD3100 Errata Sheet ES_GD3100 revision 7.0 may be obtained from the secure Docstore portal:

<https://www.docstore.nxp.com/products?path=/content/docstore/product-hierarchy/Power-train-and-electrification/HV-Gate-Driver/GD3100&folderuuiid=098c098e-94d0-4eae-b212-dfc3fa5e0efa#paging:currentPage=0|paging:number=12>

GD3100 Safety Manual UM11093 revision 6.0

1. Added row to bottom of Table 10
2. Added Section 5.2.11.6

New GD3100 Safety Manual UM11093 revision 6.0 may be obtained from the secure Docstore portal:

<https://www.docstore.nxp.com/products?path=/content/docstore/product-hierarchy/Power-train-and-electrification/HV-Gate-Driver/GD3100&folderuuiid=098c098e-94d0-4eae-b212-dfc3fa5e0efa#paging:currentPage=0|paging:number=12>

GD3100 Data Sheet revision 13.0

To achieve improvements in manufacturability and throughput, NXP is implementing minor adjustments to the spec limits on two of the GD3100 product parameters (TE: ADC total error, and Vvref: VREF regulated voltage).

Based on extensive analysis, no impact on application performance is anticipated.

New GD3100 Data Sheet revision 13.0 may be obtained from the secure Docstore portal:

<https://www.docstore.nxp.com/products?path=/content/docstore/product-hierarchy/Power-train-and-electrification/HV-Gate-Driver/GD3100&folderuuiid=098c098e-94d0-4eae-b212-dfc3fa5e0efa#paging:currentPage=0|paging:number=12>

Please see the attached documents for change details, including qualification results.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DE-01, SEM-DE-02, SEM-DS-01, and SEM-DS-02

Reason

To announce the successful qualification and release of enhanced pass 3.0 GD3100B devices for Errata removal, Safety Manual, and Data Sheet updates.

Identification of Affected Products

NXP will introduce new part numbers to identify the design change.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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